

Benchmark Survey 2004[©]

***A Comprehensive, 126 page document for
Benchmark Analysis of World Wide,
Mature IC Manufacturers containing:***

Detailed Analysis from 21 FABRICATORS

- Ten Global Corporations
- Site Participation from USA, Europe, and Asia
- Sampling from 4", 5", 6", and 8" wafer Fabs
- Minimum Feature Size .12 to 10 microns
- Sixty nine Figures of detailed Fab Demographics and Analysis
- Forty Tables of measurements, costs, yields, reliability data, operational methods, etc.
- Sixteen tables of Appendices for personalized analysis

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Survey 2004 © Published October, 2004 by YSI

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